

**Amendments to the Claims**

Please amend Claim 1. The Claim Listing below will replace all prior versions of the claims in the application:

**Claim Listing**

1. (Currently amended) A method for producing an organically bonded abrasive article, comprising the steps of:
  - a) combining an abrasive grain component and a phenolic resin component;
  - b) molding the combined components;
  - c) thermally curing the phenolic resin component for the entire period during which the phenolic resin component polymerizes in an atmosphere comprising added humidity, wherein the atmosphere has a relative humidity which exceeds normal relative humidity at a given temperature, wherein said atmosphere contacts the molded components, thereby producing the organically bonded abrasive article.
2. (Original) The method of Claim 1, wherein the abrasive grain component is an alumina grain.
3. (Previously amended) The method of Claim 1, wherein the phenolic resin component includes a phenolic resin in liquid form.
4. (Previously amended) The method of Claim 1, wherein the phenolic resin component includes a resole.
5. (Original) The method of Claim 4, wherein the resole is dissolved in water.
6. (Previously amended) The method of Claim 1, wherein the phenolic resin component includes a novolac resin.

7. (Previously amended) The method of Claim 1, wherein the method further comprises combining an organosilicon component with at least one of the abrasive grain component and the phenolic resin component of step a).
8. (Previously amended) The method of Claim 7, wherein the abrasive grain component is combined with the organosilicon component to form organosilicon-treated abrasive grain and then combined with the phenolic resin component.
9. (Previously amended) The method of Claim 8, wherein the organosilicon-treated abrasive grain is first combined with a phenolic resin in liquid form and then with a phenolic resin in powder form.
10. (Previously amended) The method of Claim 7, wherein the organosilicon component is combined with the phenolic resin component and then with the abrasive grain.
11. (Original) The method of Claim 1, wherein thermal curing is at a final cure temperature of at least about 150 °C.
12. (Original) The method of Claim 1, wherein said atmosphere further includes air.
13. (Original) The method of Claim 1, wherein said atmosphere further includes ammonia.
14. (Original) The method of Claim 1, wherein thermal curing is conducted in the presence of steam.
15. (Original) The method of Claim 14, wherein thermal curing is conducted in the presence of live steam.

16. (Original) The method of Claim 15, wherein thermal curing is conducted in a chamber and the steam is re-circulated through the chamber.
17. (Previously amended) The method of Claim 1, wherein said atmosphere is in contact with the molded components for a period of at least 5 hours.
18. (Previously amended) The method of Claim 1, wherein said atmosphere contacts the combined components prior to thermally curing the phenolic resin component.
19. (Original) The method of Claim 1, wherein the thermal curing is in a chamber held at a pressure exceeding atmospheric pressure.

Claims 20-22 (Cancelled).

23. (Previously amended) An abrasive wheel produced by a process comprising the steps of:
  - a) combining an abrasive grain component and an organosilicon component to form an organosilicon-treated abrasive grain component;
  - b) combining the organosilicon-treated abrasive grain component with a phenolic resin component;
  - c) molding the combined components to form a green body; and
  - d) thermally curing the phenolic resin component, in an atmosphere comprising humidity, wherein said atmosphere contacts the green body, thereby producing the abrasive wheel, having at least a 9 percent improvement in burst speed with respect to a standard wheel, of the same specification as said abrasive wheel.

Claims 24-26 (Canceled).

27. (Previously amended) A grinding wheel produced by a process, comprising the steps of:
- a) combining an abrasive grain component and an organosilicon component to form an organosilicon-treated abrasive grain component;
  - b) combining the organosilicon-treated abrasive grain component with a phenolic resin component;
  - c) molding the combined components to form a green body; and
  - d) thermally curing the phenolic resin component, in an atmosphere comprising humidity, wherein said atmosphere contacts the green body, thereby producing the grinding wheel, whereby the wheel has a percent wet strength retention of at least about 89.9 percent.

Claims 28-29 (Cancelled).